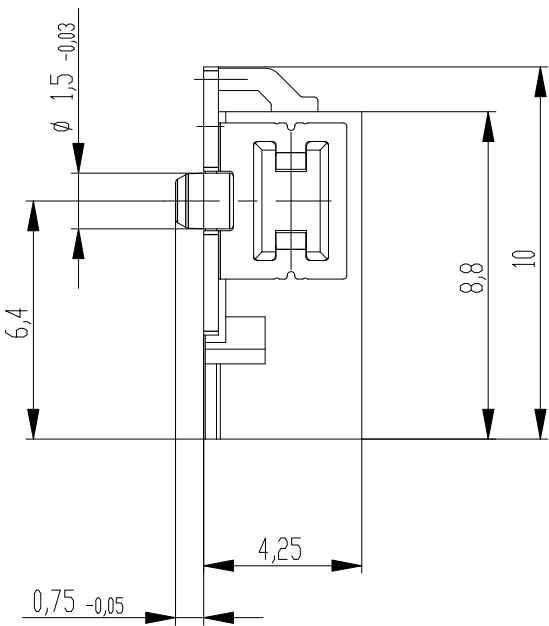
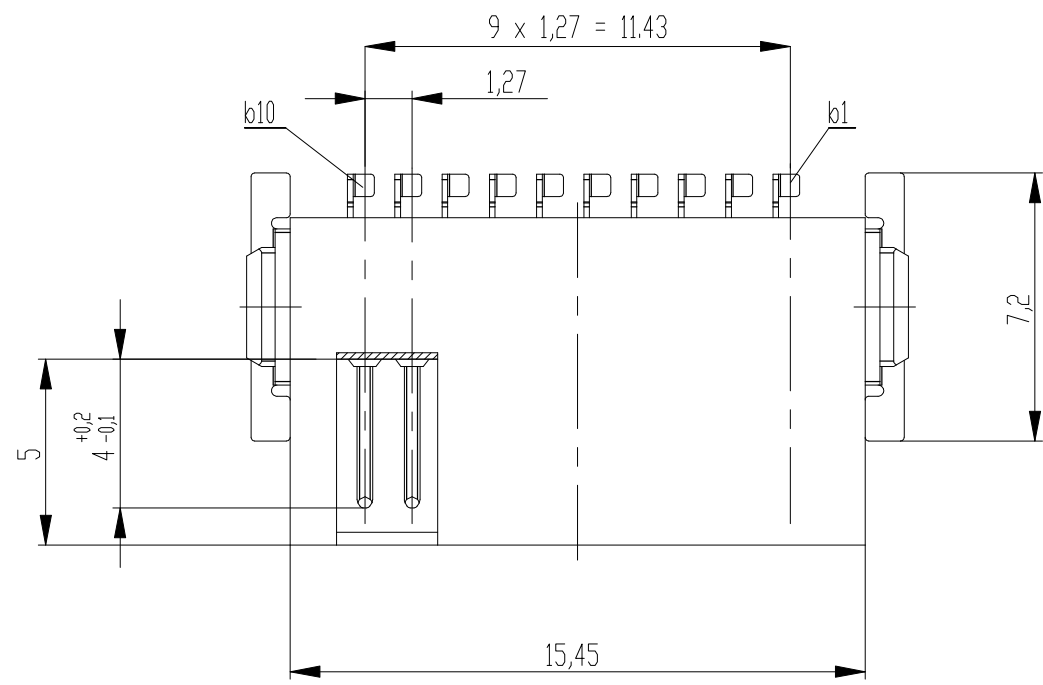
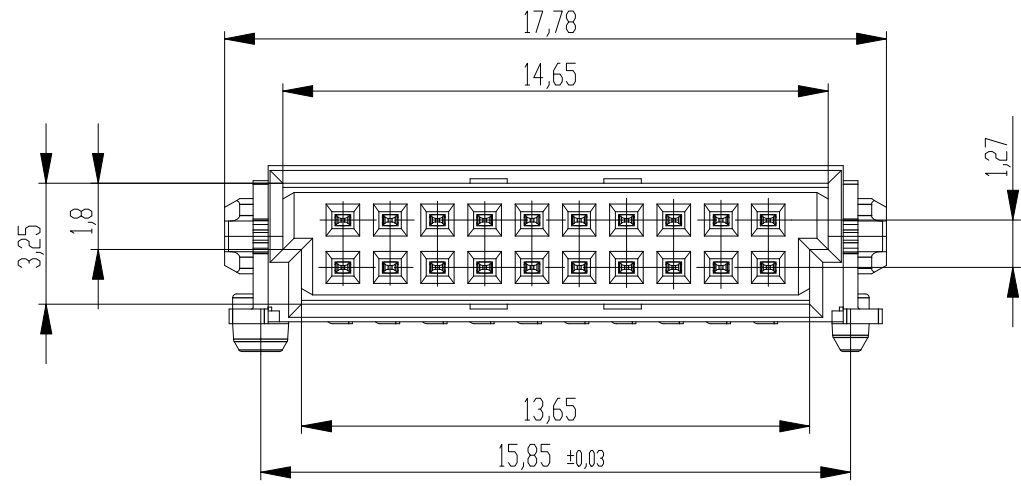
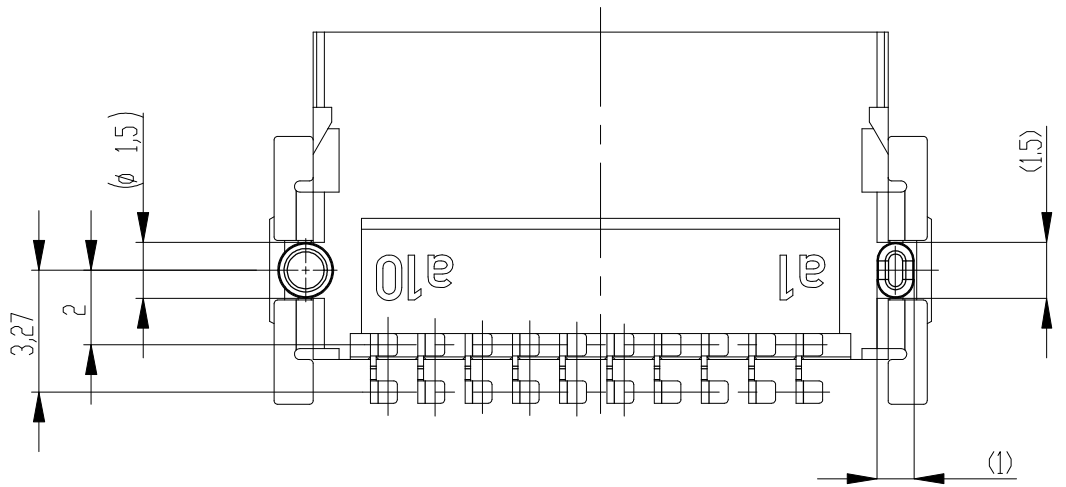
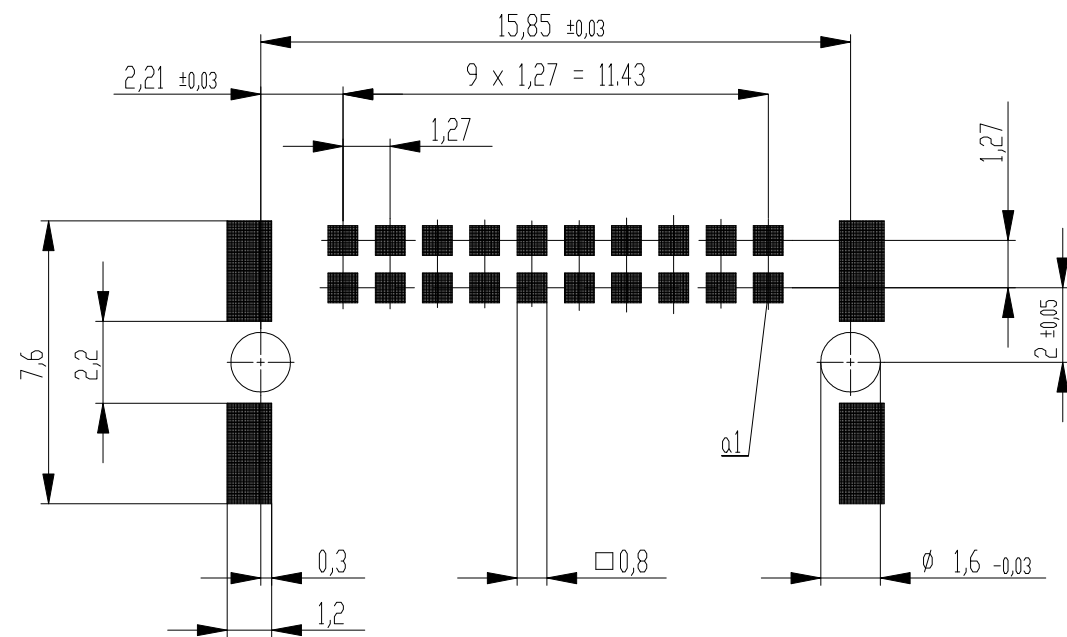
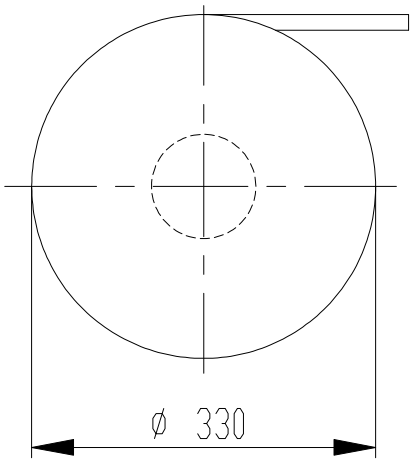




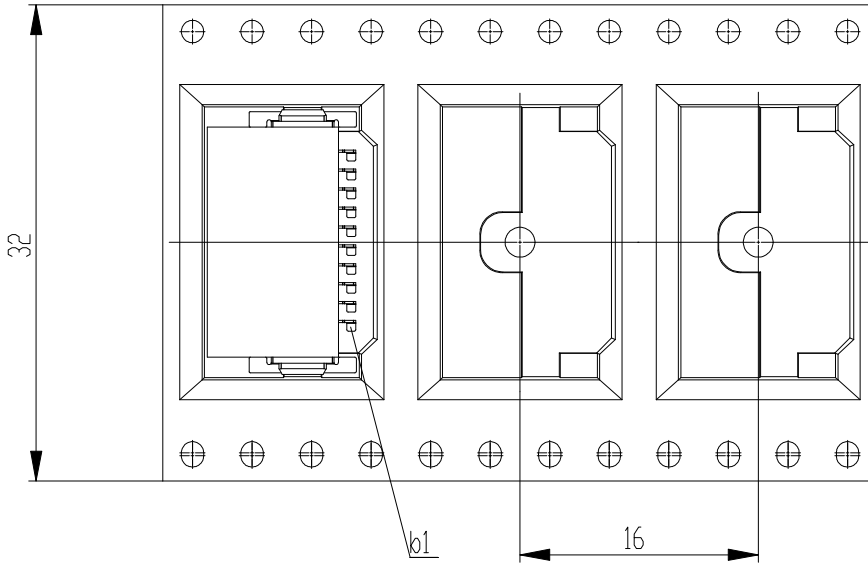
Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 560 Stück
packaging unit: 560 pcs

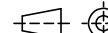


Abspulrichtung - reel off direction



Anforderungsstufe 1
performance level 1
Kontaktbereich vergoldet
mating area gold plating
Anschlussbereich verzinkt 4-6 µm
terminal area 4-6 µm tin plating
Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm

BA7-03 - Standard Bauhöhe
type7-03 - Standard Assembly Height

Dimension no.			Tolerances Din. for Information ISO 8015		 All Dimensions in mm		Scale Material		5:1	
Customer drawing: THIS DRAWING IS A CONTROLLED DOCUMENT.			Subject to modification without prior notice. Drawing will not be updated.			ERNI-Messerl. SMC-B 20-SMD-BA7-03 Male SMC-B 20-SMD-type7-03				
d		12.02.2020	 TE Connectivity			©= 354095-E				1
Index		Date				Class SMCB				A2